-	6	(700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls. and ((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor))) and network.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:09
-	6903	((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)) and ("detectors" or "sensors" or ((sens$3 or detect$4) near4 (plural$4 or several or many)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:09
-	6	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)) and ("detectors" or "sensors" or ((sens$3 or detect$4) near4 (plural$4 or several or many))))) and network.clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:10
-	48	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)) and ("detectors" or "sensors" or ((sens$3 or detect$4) near4 (plural$4 or several or many))))) and (network$3 or server or LAN or WAN or SAN or ethernet or intranet or internet)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:10
-	4	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)) and ("detectors" or "sensors" or ((sens$3 or detect$4) near4 (plural$4 or several or many))))) and (international adj2 business).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:12
-	3384	("detectors" or "sensors") and ((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:14
-	1	((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (("detectors" or "sensors") and ((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)))) and (international adj2 business).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:14
-	79	(438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (("detectors" or "sensors") and ((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:15
-	210	(438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.) and (((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)) and ("detectors" or "sensors" or ((sens$3 or detect$4) near4 (plural$4 or several or many))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 02:07

L Number	Hits	Search Text	DB	Time stamp
1	12691	438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:31
2	208	709/$.ccls. and ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:45
3	238648	(detect$3 or sens$3) with (die or die-to-die or area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:31
4	9115	(detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:31
5	2149337	"detectors" or "sensors" or ((sens$3 or detect$4) near4 (plural$4 or several or many))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:32
6	622719	"detectors" or "sensors"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:32
7	216728	((sens$3 or detect$4) near4 (plural$4 or several or many))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:32
8	2	20020103563.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:32
14	17	("5539752" | "5544256" | "5598341" | "5761064" | "5774222" | "5801965" | "5862055" | "5923430" | "5949901" | "5959459" | "5966459" | "6016562" | "6167448" | "6246787" | "6314379" | "6408219" | "6438438").PN.	USPAT	2004/07/10 15:47
17	61	5761064.URPN.	USPAT	2004/07/10 15:55
19	8	("6614520" "5737072" "6529621" "6587193").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:37
20	24357	(detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:43
21	24382	(detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 18:13

22	372	((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (distribut$43 near2 (node or process$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:03
23	42247	709/$.ccls. or ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:02
24	65	(((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (distribut$43 near2 (node or process$3))) and (709/$.ccls. or ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:58
25	2	6049895.URPN.	USPAT	2004/07/10 16:48
26	2	6629002.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:59
27	2	6711731.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 16:59
28	404	((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut$4 near2 (node)) or network$3 or ethernet or internet or LAN or WAN or SAN or area-network$3 or areanetwork$3 or computernetwork$3 or ((transfer or communicat$4) near2 (path or link$3))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:07
29	539	((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut$4 near2 (node)) or network$3 or rout$3 or ethernet or internet or LAN or WAN or SAN or area-network$3 or areanetwork$3 or computernetwork$3 or ((transfer or communicat$4) near2 (path or link$3))).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:28
30	68	(709/$.ccls. or ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))) and (((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut$4 near2 (node)) or network$3 or rout$3 or ethernet or internet or LAN or WAN or SAN or area-network$3 or areanetwork$3 or computernetwork$3 or ((transfer or communicat$4) near2 (path or link$3))).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:21
31	43	700/$.ccls. and (((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut$4 near2 (node)) or network$3 or rout$3 or ethernet or internet or LAN or WAN or SAN or area-network$3 or areanetwork$3 or computernetwork$3 or ((transfer or communicat$4) near2 (path or link$3))).clm.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:31

32	5	(700/$.ccls. and ((((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut\$4 near2 (node)) or network\$3 or rout\$3 or ethernet or internet or LAN or WAN or SAN or area-network\$3 or areanetwork\$3 or computernetwork\$3 or ((transfer or communicat\$4) near2 (path or link\$3))).clm.)) not ((709/$.ccls. or ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)))) and ((((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((distribut\$4 near2 (node)) or network\$3 or rout\$3 or ethernet or internet or LAN or WAN or SAN or area-network\$3 or areanetwork\$3 or computernetwork\$3 or ((transfer or communicat\$4) near2 (path or link\$3))).clm.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:22
34	433	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or bi-directional\$2 or bidirectional\$2)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:29
33	53	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or bi-directional\$2 or bidirectional\$2).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:40
36	74162	700/$.ccls. or (709/$.ccls. or ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:32
37	13	((((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and (duplex\$3 or bi-directional\$2 or bidirectional\$2)) and (700/$.ccls. or (709/$.ccls. or ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:32
38	2	6370487.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:42
41	0	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and 5671064.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 17:58
42	32	((detect\$3 or sens\$3 or metrology or measur\$5 or scan\$4 or SEM or (electron near2 microscop\$2) or inspect\$4 or raster\$3 or rasterscan\$4) with (die or die-to-die or area or shot or defect\$4) with (semiconductor or wafer or semi-conductor or pellicle)) and RS232	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 18:13
43	10	(US-6701259-\$ or US-6130967-\$ or US-6314379-\$ or US-5933351-\$ or US-5124927-\$ or US-5761064-\$ or US-6567770-\$ or US-6415188-\$ or US-6370487-\$).did. or (US-20020065900-\$).did.	USPAT; US-PGPUB	2004/07/10 18:57
44	4	column and ((US-6701259-\$ or US-6130967-\$ or US-6314379-\$ or US-5933351-\$ or US-5124927-\$ or US-5761064-\$ or US-6567770-\$ or US-6415188-\$ or US-6370487-\$).did. or (US-20020065900-\$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:00

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45	4	(column or composite-column) and ((US-6701259-$ or US-6130967-$ or US-6314379-$ or US-5933351-$ or US-5124927-$ or US-5761064-$ or US-6567770-$ or US-6415188-$ or US-6370487-$).did. or (US-20020065900-$).did.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:01
46	1	(column or composite-column) and (("6614520" "5737072" "6529621" "6587193").pn.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:03
47	1182	((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:02
48	183	(column or composite-column) and (((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:03
49	29	(column or composite-column).clm. and (((detect$3 or sens$3 or metrology or measur$5 or scan$4 or SEM or (electron near2 microscop$2) or inspect$4 or raster$3 or rasterscan$4) with (die or die-to-die or area or shot or defect$4) with (semiconductor or wafer or semi-conductor or pellicle)) and ((438/5-18.ccls. or 700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 19:03
-	4	("6614520" "5737072").pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 18:09
-	7297	438/5-18.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 19:07
-	5563	700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 19:07
-	82	(SEM or (scan$4 near2 electron)) and (709/$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/10 15:31
-	389	700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls. and ((detect$3 or sens$3) with (die or die-to-die or area))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 21:55
-	61	700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls. and ((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 22:09
-	23	(700/1-4,19,20,51,59,90,95,96,108-110,117,121.ccls. and ((detect$3 or sens$3) with (die or die-to-die or area) with (semiconductor or wafer or semi-conductor))) and network	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/09 21:58

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